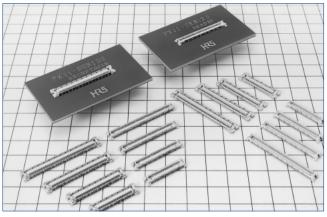
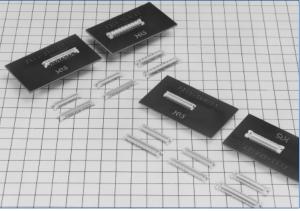
0.5mm Pitch Connectors with Ground Plate for 2mm to 3mm High-Speed Board-to-Board Connections

FX11 Series

Stacking height : 2mm



Stacking height : 2.5mm, 3mm



Features

1. Low Profile Design

The board-to-board mating height of 2mm, 2.5mm and 3mm suits smaller, thinner case designs. (Fig.2)

2. Improved Transmission Efficiency Between Boards

Transmission characteristics have been improved through a design that fixes ground plates to both sides of the header and receptacle.

3. 10 Signal:1 Ground Arrangement

Signal and ground are arranged in a ratio of 10 : 1 with the ground plate connected to the board Via SMT. The ground stability achieved serves to reduce noise. (Fig.1)

4. Metal Fittings for Added Strength

Metal fittings provide for greater adhesion to the board, which protects the connector against sheaning forces. The unique connector design provides a connection between the fitting and the ground plate for a stronger ground.

5. Suited to High-Density Applications

The signal contact pitch of 0.5mm affords a compact connector, and reduces mounting space on the board.

6. Structure Prevents Solder Wicking

A solder gap has been designed into the contact SMT portion to prevent solder wicking. (Fig.3)

7. High Contact Reliability

Effective wipe length is 0.55mm (2mm height) and 1mm(2.5mm, 3mm height) for signal contacts.

8. Optional Ground Plate

An alternate style is also available without the ground plate. The space provided by the absence of the ground plate is filled with additional signal contacts.

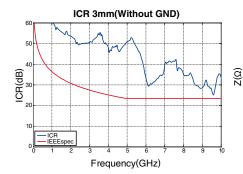
Signal Integrity Features

Insertion-Loss-to-Crosstalk Ratio (ICR)

The insertion-loss-to-crosstalk ratio (ICR) with five differential FEXT aggressors meets the extrapolated IEEE802.3ap specification to 10⁺ Gbps.

Differential Impedance

The differential impedance is $100 + - 10\Omega$ for FX11 at 50 ps rise time(20% to 80%).



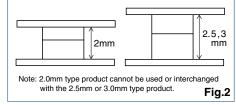


Ground plate and metal fitting make contact

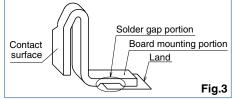
Fig.1

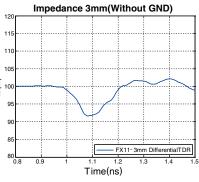
Stacking Height Variation

Metal fitting



Structure Prevent Solder Wicking





In cases where the application will demand a high level of reliability, such as automotive, please contact a company representative for further information.

Stacking height variation

• With ground plate

Receptacle	FX11L#-*P / *-SV
FX11L#-*S / *-SV	2mm

Receptacle	FX11#-*P / *-SV	FX11#-*P / *-SV0.5
FX11#-*S / *-SV	2.5mm	3mm

Without ground plate

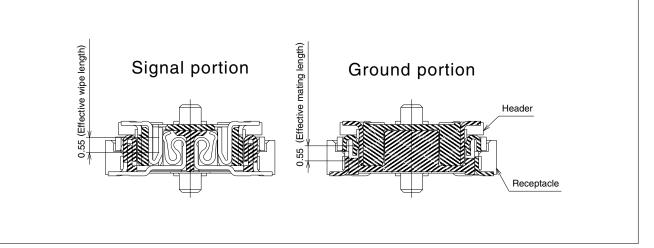
Receptacle Header	FX11L#-*P-SV	
FX11L#-*S-SV	2mm	
Receptacle Header	FX11#-*P-SV	FX11#-*P-SV0.5
FX11#-*S-SV	2.5mm	3mm

Note 1: The thickness of the solder paste is not included in the stacking height.

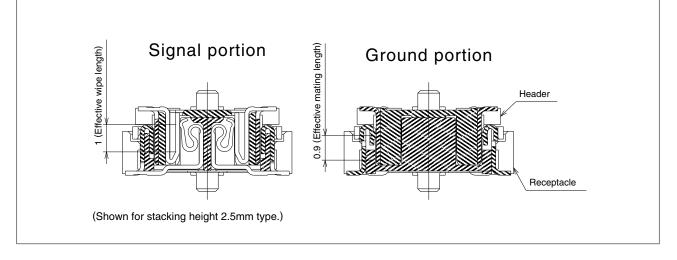
Note 2: 2mm type and 2.5mm, 3mm type, with ground plate type and without ground type are not mated with each other.

Cross section of mating

Stacking height : 2mm



• Stacking height : 2.5mm, 3mm



Stacking height : 2mm

Product Specifications

Rating	Rated current Rated voltage		Operating temperature range Operating humidity range	-55 to +85℃ Relative humic (No condensat	lity 95% or less	Storage temperature range Storage humidity range	-10 to +60°C (Note 1) 40 to 70% (Note 1)		
	Item		Requirements			Conditions			
1. Insula	ation resistance	100MΩ or g	reater		Measured a	at 100V DC			
2. Withs	standing voltage	No flashove	er or breakdown		150V AC a	oplied for 1 minute			
3. Conta	act resistance	60mΩ or les	SS		Measured a	at 100mA			
4. Vibrat	tion resistance		al discontinuity for 1μ s o ed, cracked or loose part		Frequency : 10 to 55Hz, amplitude of 0.75mm in 3 directions, 10 cycles each				
5. Shoo	ck resistance	2	al discontinuity for 1μ s o ed, cracked or loose part	•	Acceleration of 490m/s ² , 11ms duration, sine half-wave waveform, for 3 cycles in the both directions of each of the 3 axes				
6. Hum resis	nidity stance		ance of 70m Ω or less, insulatio ater, No damaged, cracked or		Temperatur duration 96	re of 40℃, humidity of h	90 to 95%,		
7. Tem	perature cycle	<u>ו</u>	ance of 70m Ω or less, insulatio ater, No damaged, cracked or		f Temperature : -55° C \rightarrow 15 to 35° C \rightarrow 85 $^{\circ}$ C \rightarrow 15 to 35° C Time : 30 min. \rightarrow 2 to 3 min. \rightarrow 30 min. \rightarrow 2 to 3 min. for 5 cycles				
8. Mati	ng cycles		Contact resistance of 70mΩ or less No damaged, cracked or loose parts						
	ler heat stance	No melting o	f resin portion which affects	performance		the recommended ten ron temperature : 360°			

Note 1 : The term "storage" refers to the long-term-storage status of unused items before mounting on the PCB. The operating temperature/humidity ranges apply to the unmated state after board mounting.

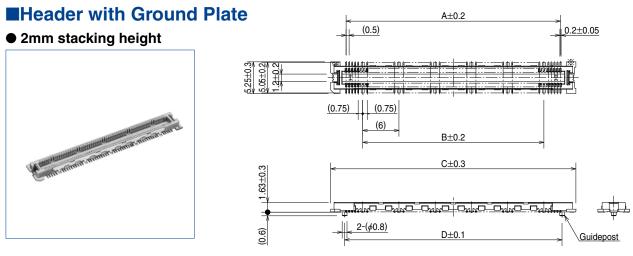
Materials / Finish

Part	Material		Finish	Remarks
Insulator	LCP	Beige		UL94V-0
Contonto	Copper alloy	Header	Engagement Area : Gold plating of $0.1 \mu m$	
Contacts	Phosphor bronze	Receptacle	Termination Area : Flash plating	
Ground plate	Phosphor bronze	Tin plating		
Metal fitting	Dhaanhar branza	Tin plating		
Metal plate	Phosphor bronze	Tin plating		

Product Number Structure

Refer to the chart below when determining the product specifications from the product number. Please select from the product numbers listed in this catalog when placing orders.

Type With Gro	ound Plate	FX11L	# -	*	P - / * - SV (**)		
		1	2		 ④ ● ● ● ● ● ● 		
Type Without G	round Plate	FX11L	<u>#</u> -	*	$\frac{P}{4} - \frac{SV}{6} \frac{(**)}{6}$		
 Serie 	es name : FX1	1L		4	Connector type		
2 Forn	n Symbol A	: With guide pos	st		P : Header		
	В	: Without guide	post		S : Receptacle		
🕄 Num	ber of contact	ts Type with grou	nd plate	6	Contact form		
		al/Ground : 60/			SV : Straight SMT		
	100/10, 120/12		6	Blank, (71) : Tray packaging (Without pick-and-place tape)			
	Type without ground plate				(21),(91) : Embossed tape packaging (Without pick-and-place tape)		
	Signal : 68, 92, 116, 140				(22),(92) : Embossed tape packaging (With pick-and-place tape)		



Unit : mm

Part No.	HRS No.	No. of C	Contacts	Δ	В	С	D	Е	F	Remarks	RoHS
Pan No.		Signal	Ground	A	D	C	D			nemarks	попо
FX11LA-60P/6-SV(71)	573-0002-7 71	60	6	17.5	12	22.6	18	19.4	25.5		
FX11LA-80P/8-SV(71)	573-0003-0 71	80	8	23.5	18	28.6	24	25.4	31.5		
FX11LA-100P/10-SV(71)	573-0004-2 71	100	10	29.5	24	34.6	30	31.4	37.5	With guideposts	
FX11LA-120P/12-SV(71)	573-0005-5 71	120	12	35.5	30	40.6	36	37.4	43.5		Yes
FX11LB-60P/6-SV(71)	573-0012-0 71	60	6	17.5	12	22.6		19.4	25.5		res
FX11LB-80P/8-SV(71)	573-0013-3 71	80	8	23.5	18	28.6		25.4	31.5		
FX11LB-100P/10-SV(71)	573-0014-6 71	100	10	29.5	24	34.6		31.4	37.5	Without guideposts	
FX11LB-120P/12-SV(71)	573-0015-9 71	120	12	35.5	30	40.6		37.4	43.5		

[Specifications number] - **, (**)

(71) : Tray packaging

(91) : Embossed tape packaging (Without pick-and-place tape)

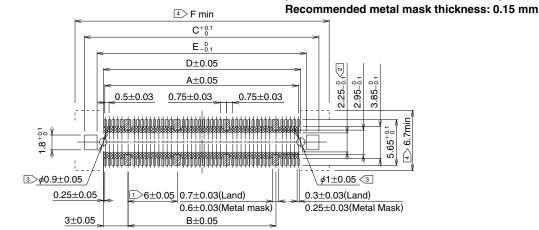
(92) : Embossed tape packaging (With pick-and-place tape)

Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

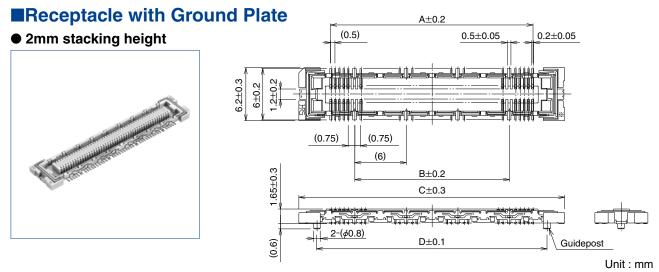
Recommended Land Pattern Dimensions (Metal Mask Dimensions)



Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

2 The cross-hatched area 🖾 inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.

- 3Not required in products without guideposts.
- (4) Do not mount a part other than this product in the area of []]. Doing so will prevent the engagement of this and the mating connector.



Part No.	HRS No.	No. of C	Contacts	Α	В	С	D	Е	F	Remarks	RoHS
Part No.		Signal	Ground	A	D	C	D		Г	nemarks	попо
FX11LA-60S/6-SV(71)	573-0102-1 71	60	6	17.5	12	25	20.8	25.4	22.2		
FX11LA-80S/8-SV(71)	573-0103-4 71	80	8	23.5	18	31	26.8	31.4	28.2	Mith suidenests	
FX11LA-100S/10-SV(71)	573-0104-7 71	100	10	29.5	24	37	32.8	37.4	34.2	With guideposts	
FX11LA-120S/12-SV(71)	573-0105-0 71	120	12	35.5	30	43	38.8	43.4	40.2		Yes
FX11LB-60S/6-SV(71)	573-0112-5 71	60	6	17.5	12	25	—	25.4	22.2		res
FX11LB-80S/8-SV(71)	573-0113-8 71	80	8	23.5	18	31		31.4	28.2		
FX11LB-100S/10-SV(71)	573-0114-0 71	100	10	29.5	24	37	—	37.4	34.2	Without guideposts	
FX11LB-120S/12-SV(71)	573-0115-371	120	12	35.5	30	43		43.4	40.2		

(71) : Tray packaging (Without pick-and-place tape)

(91) : Embossed tape packaging (Without pick-and-place tape)

(92) : Embossed tape packaging (With pick-and-place tape)

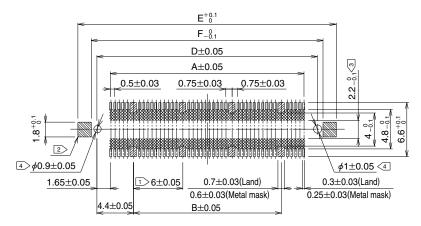
Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm



Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

2 Cross-hatched portions, 2 places on both sides, indicate the metal fittings.

3 The cross-hatched area inside the SMT land may come into contact with the connector contacts

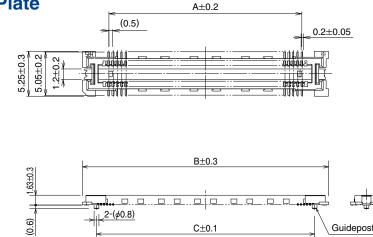
and thus care should be taken that the pattern does not extend beyond the SMT land width.

(4)Not required in products without guideposts.

Header without Ground Plate

2mm stacking height





C±0.1

Guidepost

						-	-	U	nıt : mm
Part No.	HRS No.	No. of Contacts	Α	В	с	D	Е	Remarks	RoHS
Part No.		Signal	A	D		D		nemarks	попо
FX11LA-68P-SV(**)	573-0042-1 **	68	16.5	22.6	18	19.4	25.5		
FX11LA-92P-SV(**)	573-0043-4 **	92	22.5	28.6	24	25.4	31.5	With avidencete	
FX11LA-116P-SV(**)	573-0044-7 **	116	28.5	34.6	30	31.4	37.5	With guideposts	
FX11LA-140P-SV(**)	573-0045-0 **	140	34.5	40.6	36	37.4	43.5		Yes
FX11LB-68P-SV(**)	573-0052-5 **	68	16.5	22.6		19.4	25.5		res
FX11LB-92P-SV(**)	573-0053-8 **	92	22.5	28.6		25.4	31.5	With out outdop onto	
FX11LB-116P-SV(**)	573-0054-0 **	116	28.5	34.6		31.4	37.5	Without guideposts	
FX11LB-140P-SV(**)	573-0055-3 **	140	34.5	40.6		37.4	43.5		

[Specifications number] - **, (**)

Blank : Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

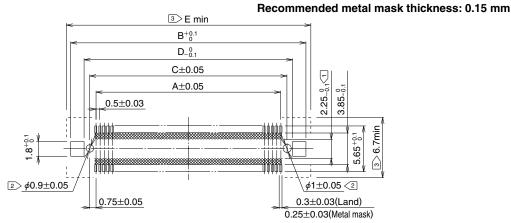
: Embossed tape packaging (With pick-and-place tape) (22)

Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

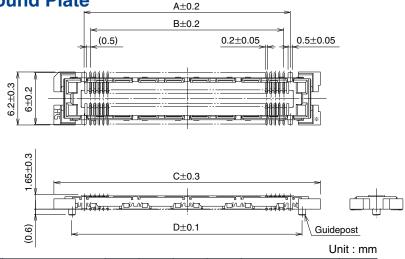
Recommended Land Pattern Dimensions (Metal Mask Dimensions)



- Note 1 The cross-hatched area inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
 - 2 Not required in products without guideposts.
 - of this and the mating connector.

Receptacle without Ground Plate

• 2mm stacking height



Part No.	HRS No.	No. of Contacts	Contacts A		с	D	Remarks	RoHS
Fait NO.		Signal	A	В			nemaiks	попо
FX11LA-68S-SV(**)	573-0142-6 **	68	18	16.5	25	20.8		
FX11LA-92S-SV(**)	573-0143-9 **	92	24	22.5	31	26.8	With suideneete	
FX11LA-116S-SV(**)	573-0144-1 **	116	30	28.5	37	32.8	With guideposts	
FX11LA-140S-SV(**)	573-0145-4 **	140	36	34.5	43	38.8		Yes
FX11LB-68S-SV(**)	573-0152-0 **	68	18	16.5	25			res
FX11LB-92S-SV(**)	573-0153-2 **	92	24	22.5	31		With out outdop onto	
FX11LB-116S-SV(**)	573-0154-5 **	116	30	28.5	37		Without guideposts	
FX11LB-140S-SV(**)	573-0155-8 **	140	36	34.5	43			

[Specifications number] - **, (**)

Blank : Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

(22) : Embossed tape packaging (With pick-and-place tape)

Note 1 : There is no polarity in terms of board mounting for this product.

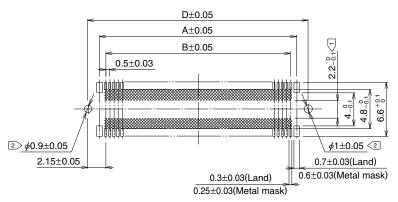
Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm

HS 7



Note 1 The cross-hatched area inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
 2 Not required in products without guideposts.

Stacking height : 2.5mm, 3mm

Product Specifications

Rating Rated current 0.3A Operating temperature range -55 to +85°C Rated voltage 50V AC Operating humidity range Relative humidity 95% or less Storage temperature range -10 to +60 (No condensation) Storage humidity range 40 to 70%		
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Item	Requirements	Conditions
1. Insulation resistance	100MΩ or greater	Measured at 100V DC
2. Withstanding voltage	No flashover or breakdown	150V AC applied for 1 minute
3. Contact resistance	70mΩ or less	Measured at 100mA
4. Vibration resistance	No electrical discontinuity for 1μ s or greater No damaged, cracked or loose parts	Frequency : 10 to 55Hz, amplitude of 0.75mm in 3 directions,10 cycles each
5. Shock resistance	No electrical discontinuity for 1μ s or longer No damaged, cracked or loose parts	Acceleration of 490m/s ² , 11ms duration, sine half-wave waveform, for 3 cycles in the both directions of each of the 3 axes
6. Humidity resistance	Contact resistance of $80m\Omega$ or less, insulation resistance of $100M\Omega$ or greater, No damaged, cracked or loose parts	Temperature of 40℃, humidity of 90 to 95%, duration 96h
7. Temperature cycle	Contact resistance of $80m\Omega$ or less, insulation resistance of $100M\Omega$ or greater, No damaged, cracked or loose parts	$\begin{array}{l} \mbox{Temperature}:-55^{\circ}\!\!\mathbb{C}\rightarrow15\mbox{ to }35^{\circ}\!\!\mathbb{C}\rightarrow85^{\circ}\!\!\mathbb{C}\rightarrow15\mbox{ to }35^{\circ}\!\!\mathbb{C}\\ \mbox{Time}:30\mbox{ min.}\rightarrow2\mbox{ to }3\mbox{ min.}\rightarrow30\mbox{ min.}\rightarrow2\mbox{ to }3\mbox{ min. for }5\mbox{ cycles} \end{array}$
8. Mating cycles	Contact resistance of $80m\Omega$ or less No damaged, cracked or loose parts	50 times
9. Solder heat resistance	No melting of resin portion which affects performance	Reflow : At the recommended temperature profile Soldering iron temperature : 360° C for 5 seconds

Note 1 : The term "storage" refers to the long-term-storage status of unused items before mounting on the PCB. The operating temperature/humidity ranges apply to the unmated state after board mounting.

Materials / Finish

Part	Material		Remarks	
Insulator	LCP	Beige		UL94V-0
0	Copper alloy	Header	Engagement Area : Gold plating of $0.1 \mu m$	
Contacts	Phosphor bronze	Receptacle	Termination Area : Flash plating	
Ground plate	Phosphor bronze	Tin plating		
Metal fitting	Dhaanhar branna	Tip plating		
Metal plate	Phosphor bronze	Tin plating		

Product Number Structure

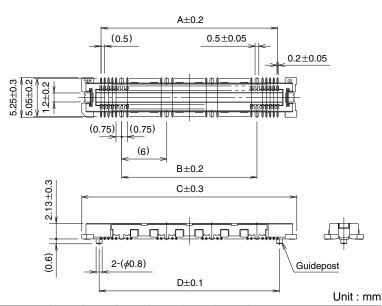
Refer to the chart below when determining the product specifications from the product number. Please select from the product numbers listed in this catalog when placing orders.

Type With Ground Plate FX11 # - > ① ② - >	<u>k</u> <u>P</u> / <u>*</u> - <u>SV</u> <u>0.5</u> <u>(**)</u> [®]
Type Without Ground Plate FX11 # - > • • • • • •	$\frac{k}{9} \frac{P}{4} - \frac{SV}{6} \frac{0.5}{6} \frac{(**)}{7}$
Series name : FX11	Connector type
Form Symbol A : With guide post B : Without guide post	P : Header S : Receptacle
 Number of contacts Type with ground plate Signal/Ground:60/6, 80/8, 100/10 Type without ground plate Signal : 80, 100 	 6 Contact form SV : Straight SMT 6 Product height Blank: Standard 0.5 : Standard + 0.5mm 7 Blank, (71) : Tray packaging (Without pick-and-place tape) (21),(91) : Embossed tape packaging (Without pick-and-place tape) (22),(92) : Embossed tape packaging (With pick-and-place tape)

Header with Ground Plate

2.5mm stacking height





Part No.	HRS No.	No. of Contacts		Δ	В	С	D	Е	F	Remarks	RoHS
Part No.	HRS NO.	Signal	Ground	A	D	C				Tiemano	попо
FX11A-60P/06-SV(71)	573-0502-0 71	60	6	17.5	12	22.6	18	19.4	25.5		
FX11A-80P/08-SV(71)	573-0503-2 71	80	8	23.5	18	28.6	24	25.4	31.5	With guideposts	
FX11A-100P/10-SV(71)	573-0504-5 71	100	10	29.5	24	34.6	30	31.4	37.5		Yes
FX11B-60P/06-SV(71)	573-0512-3 71	60	6	17.5	12	22.6	—	19.4	25.5		res
FX11B-80P/08-SV(71)	573-0513-6 71	80	8	23.5	18	28.6	—	25.4	31.5	Without guideposts	
FX11B-100P/10-SV(71)	573-0514-9 71	100	10	29.5	24	34.6		31.4	37.5		

[Specifications number] - **, (**)

(71) : Tray packaging (Without pick-and-place tape)

(91) : Embossed tape packaging (Without pick-and-place tape)

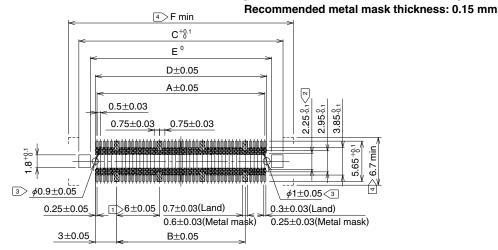
(92) : Embossed tape packaging (With pick-and-place tape)

Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

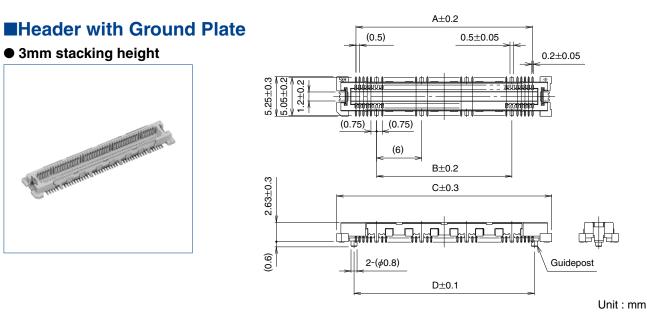
Recommended Land Pattern Dimensions (Metal Mask Dimensions)



Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

- 2 The cross-hatched area inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
 3 Not required in products without guidenests.
- Not required in products without guideposts.
- (4) Do not mount a part other than this product in the area of [...]. Doing so will prevent the engagement of this and the mating connector.

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Part No.	HRS No.	No. of C	No. of Contacts		В	С	D	Е	E	Remarks	RoHS
Part No.		Signal	Ground	and A			D		Г	nemarks	попо
FX11A-60P/6-SV0.5(71)	573-0602-4 71	60	6	17.5	12	22.6	18	19.4	25.5	With	
FX11A-80P/8-SV0.5(71)	573-0603-7 71	80	8	23.5	18	28.6	24	25.4	31.5	guideposts	
FX11A-100P/10-SV0.5(71)	573-0604-0 71	100	10	29.5	24	34.6	30	31.4	37.5	guideposis	Yes
FX11B-60P/6-SV0.5(71)	573-0612-8 71	60	6	17.5	12	22.6	—	19.4	25.5	Without	res
FX11B-80P/8-SV0.5(71)	573-0613-0 71	80	8	23.5	18	28.6	—	25.4	31.5	guideposts	
FX11B-100P/10-SV0.5(71)	573-0614-3 71	100	10	29.5	24	34.6		31.4	37.5	guidoposis	

(71) : Tray packaging (Without pick-and-place tape)

(91) : Embossed tape packaging (Without pick-and-place tape)

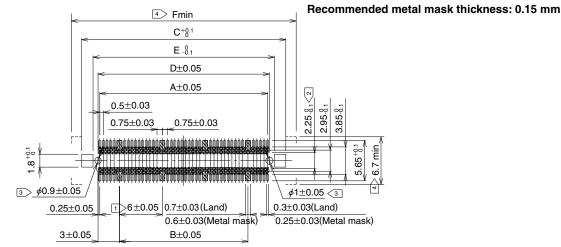
(92) : Embossed tape packaging (With pick-and-place tape)

Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

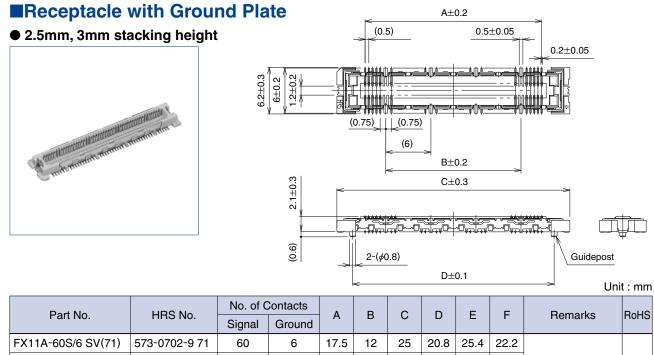
Recommended Land Pattern Dimensions (Metal Mask Dimensions)



Note 1 Cross-hatched portions, totaling n places, indicate the ground circuits.

2 The cross-hatched area inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.

- 3Not required in products without guideposts.
- (4) Do not mount a part other than this product in the area of []]. Doing so will prevent the engagement of this and the mating connector.



FX11A-80S/8 SV(71)	573-0703-1 71	80	8	23.5	18	31	26.8	31.4	28.2	With guideposts	
FX11A-100S/10 SV(71)	573-0704-4 71	100	10	29.5	24	37	32.8	37.4	34.2		Yes
FX11B-60S/6 SV(71)	573-0712-2 71	60	6	17.5	12	25	_	25.4	22.2		res
FX11B-80S/8 SV(71)	573-0713-5 71	80	8	23.5	18	31	_	31.4	28.2	Without guideposts	
FX11B-100S/10 SV(71)	573-0714-8 71	100	10	29.5	24	37		37.4	34.2		

(71) : Tray packaging (Without pick-and-place tape)

(91) : Embossed tape packaging (Without pick-and-place tape)

(92) : Embossed tape packaging (With pick-and-place tape)

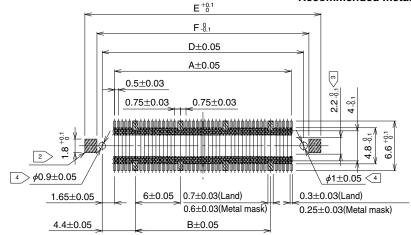
Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm



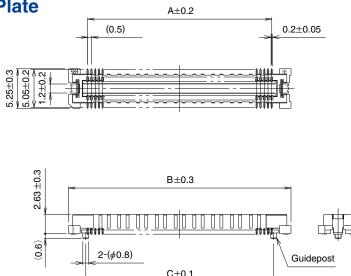
Note 1>Cross-hatched portions, totaling n places, indicate the ground circuits.

- 2 Cross-hatched portions, totaling 2 places, indicate the metal fittings.
- 3 The cross-hatched area inside the SMT land may come into contact with the connector contacts
- and thus care should be taken that the pattern does not extend beyond the SMT land width.
 - $\boxed{4}$ Not required in products without guideposts.

Header without Ground Plate

2.5mm stacking height





Unit : mm

Part No.	HRS No.	No. of Contacts	A	В	С	D	Е	Remarks	RoHS
		Signal							
FX11A-80P-SV(**)	573-0548-0 **	80	19.5	24.6	20	21.4	27.5	With guideposts	
FX11A-100P-SV(**)	573-0543-7 **	100	24.5	29.6	25	26.4	32.5	With guideposis	Yes
FX11B- 80P-SV(**)	573-0558-4 **	80	19.5	24.6		21.4	27.5	Without guideposts	res
FX11B-100P-SV(**)	573-0553-0 **	100	24.5	29.6		26.4	32.5	will lour guideposis	

[Specifications number] - **, (**)

Blank : Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

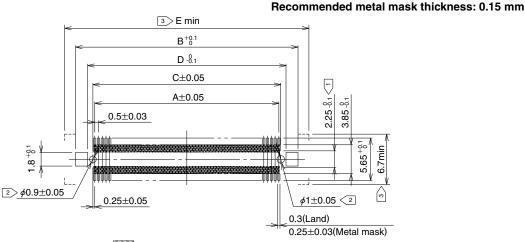
(22) : Embossed tape packaging (With pick-and-place tape)

Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

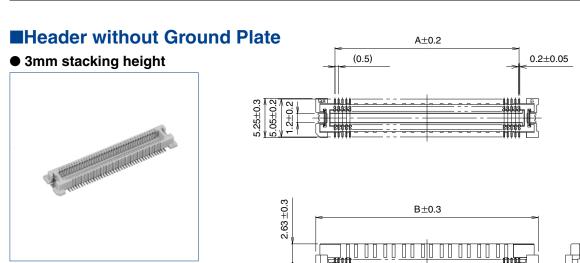
Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)



Note 1) The cross-hatched area 🖾 inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.

- $\boxed{2}$ Not required in products without guideposts.



(0.6)



HS 13

Guidepost

Part No.	HRS No.	No. of Contacts Signal	A	в	с	D	Е	Remarks	RoHS
		eignai							
FX11A-80P-SV0.5(**)	573-0648-5 **	80	19.5	24.6	20	21.4	27.5	With avaidancete	
FX11A-100P-SV0.5(**)	573-0643-1 **	100	24.5	29.6	25	26.4	32.5	With guideposts	Vaa
FX11B-80P-SV0.5(**)	573-0658-9 **	80	19.5	24.6		21.4	27.5	Without quideposts	Yes
FX11B-100P-SV0.5(**)	573-0653-5 **	100	24.5	29.6		26.4	32.5	Without guideposts	

2-(ø0.8)

C±0.1

[Specifications number] - **, (**)

Blank : Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

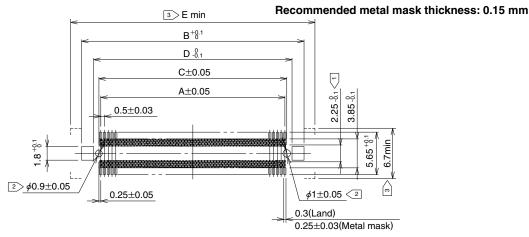
(22) : Embossed tape packaging (With pick-and-place tape)

Note 1 : There is no polarity in terms of board mounting for this product.

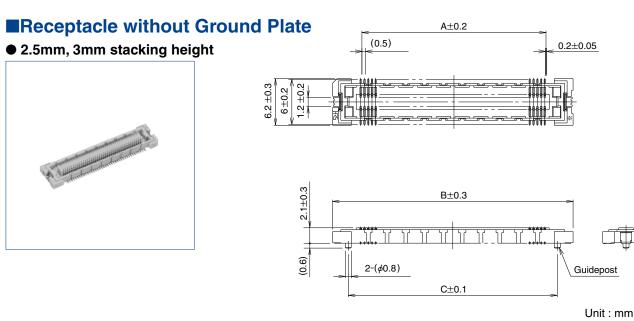
Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

Recommended Land Pattern Dimensions (Metal Mask Dimensions)



- Note 1) The cross-hatched area 2 inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
 - 2Not required in products without guideposts.



Part No.	HRS No.	No. of Contacts	Α	в	с	D	Е	Remarks	RoHS
Fait No.	TING NO.	Signal		D				Hemains	10113
FX11A-80S-SV(**)	573-0748-0 **	80	19.5	27	22.8	27.4	24.2	With guideposts	
FX11A-100S-SV(**)	573-0743-6 **	100	24.5	32	27.8	32.4	29.2	with guideposts	Yes
FX11B-80S-SV(**)	573-0758-3 **	80	19.5	27		27.4	24.2	Without guideposts	res
FX11B-100S-SV(**)	573-0753-0 **	100	24.5	32		32.4	29.2	without guideposts	

Blank : Tray packaging (Without pick-and-place tape)

(21) : Embossed tape packaging (Without pick-and-place tape)

(22) : Embossed tape packaging (With pick-and-place tape)

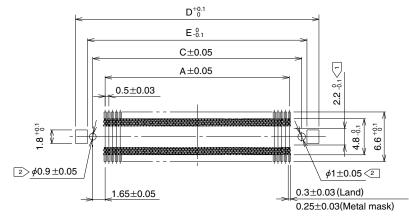
Note 1 : There is no polarity in terms of board mounting for this product.

Note 2 : The coplanarity of this product's SMT leads is 0.1 mm or less.

Note 3 : Please order embossed tape packaged items by the reel. (1,000 pcs/reel)

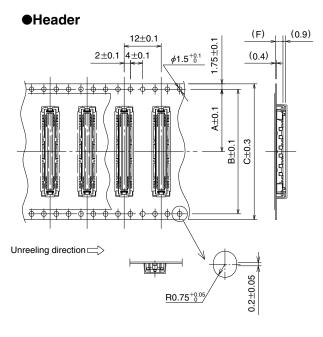
Recommended Land Pattern Dimensions (Metal Mask Dimensions)

Recommended metal mask thickness: 0.15 mm



Note 1) The cross-hatched area 2 inside the SMT land may come into contact with the connector contacts and thus care should be taken that the pattern does not extend beyond the SMT land width.
 2) Not required in products without guideposts.

Embossed Carrier Tape Dimensions



					Un	<u>it : mm</u>	
Insertion Connector	Α	В	С	D	E	F	
FX11L #-60P/6-SV	20.2	40.4	44	45.5	50.5		
FX11L #-80P/8-SV	20.2	40.4	44	45.5	50.5		
FX11L #-100P/10 -SV	26.2	EQ 4	EG	50	64		
FX11L #-120P/12 -SV	26.2	52.4	56	59	64	1 00	
FX11L #-68P-SV	20.2	40.4	44	45.5	50.5	1.98	
FX11L #-92P-SV	20.2	40.4	44	45.5	50.5		
FX11L #-116P-SV	26.2	EQ 4	EG	50	64		
FX11L #-140P-SV	26.2	52.4	56	59	04		
FX11#-60P/6-SV	20.2	40.4	44	45.5	50.5		
FX11#-80P/8-SV	20.2	40.4	44	45.5	50.5		
FX11#-100P/10-SV	26.2	52.4	56	59	64	2.48	
FX11#-80P-SV	20.2	40.4	44	45.5	50.5		
FX11#-100P-SV	20.2	40.4	44	45.5	50.5		
FX11#-60P/6-SV0.5	20.2	40.4	44	45.5	50.5		
FX11#-80P/8-SV0.5	20.2	40.4	44	45.5	50.5		
FX11#-100P/10-SV0.5	26.2	52.4	56	59	64	2.98	
FX11#-80P-SV0.5	20.2	40.4	44	45.5	50.5		
FX11#-100P-SV0.5	20.2	40.4	44	45.5	50.5		
.							

Note 1 : There is no polarity in terms of embossed tape packaging for this product.

Note 2 : Left figure is representative of products with ground plates.

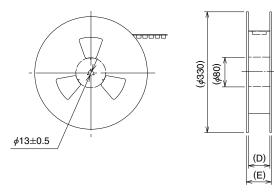
Receptacle (0.9) 12±0.1 (F) 1.75±0.1 2±0.1 4±0.1 φ1.5^{+0.1} (0.4) •++ -0 ₩ -Φ -0 0 a consideration of the second A±0.1 C±0.3 B±0.1 ቅ $\phi \phi$ - 0 0 Φ -\$ -\$(\$ -0 Unreeling direction ur p 0.2±0.05 R0.75^{+0.05}

A 20.2	В	С	D	Е	-
20.2			-	E	F
20.2	40.4	44	45.5	50.5	
	40.4	44	45.5	50.5	
06.0	EO 4	FC	50	64	
20.2	<u>5</u> 2.4	90	59	04	2
00.0	40.4	4.4			2
20.2	40.4	44	45.5	50.5	
00.0	50.4	50	50	64	
20.2	52.4	90	59	64	
00.0	40.4	4.4		50 F	
20.2	40.4	44	45.5	50.5	
26.2	52.4	56	59	64	2.45
20.2	40.4	11	45.5	50 F	
20.2	40.4	44	45.5	50.5	
	20.2	20.2 40.4 20.2 52.4 20.2 40.4 20.2 40.4 26.2 52.4 20.2 40.4 20.2 40.4	20.2 40.4 44 26.2 52.4 56 20.2 40.4 44 26.2 52.4 56 20.2 40.4 44 26.2 52.4 56 20.2 40.4 44	20.2 40.4 44 45.5 26.2 52.4 56 59 20.2 40.4 44 45.5 20.2 40.4 44 45.5 26.2 52.4 56 59 20.2 40.4 44 45.5 26.2 52.4 56 59 20.2 40.4 44 45.5	20.2 40.4 44 45.5 50.5 26.2 52.4 56 59 64 20.2 40.4 44 45.5 50.5 26.2 52.4 56 59 64 26.2 52.4 56 59 64

Note 1 : There is no polarity in terms of embossed tape packaging for this product.

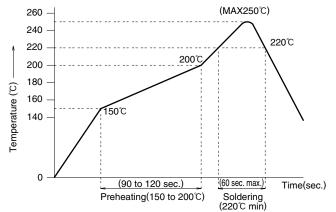
Note 2 : Left figure is representative of products with ground plates.

Reel Dimensions





Recommended Temperature Profile



Note : The temperature profile indicates the maximum temperature of the connector surfaces at the highest point from the PCB mounting surface.

Washing Conditions

Organic Solvent Washing

Solvent	Room temperature washing	Heated washing
IPA(Isopropyl alcohol)	Yes	Yes

Water Type Washing

When using water type cleaning agents (e.g., terpene, and alkali saponifiers), select the cleaning agent based on the documentation issued by the various manufacturers of cleaning agents which describes the effects on metals and resins. Be careful that parts are not left with moisture remaining on them.

Washing Precautions

Residual flux or cleaning agent on the contacts when washing with organic solvents or water type cleaners can give rise to the deterioration of electrical performance. In this regard it is important to check whether a thorough washing has been performed.

Connector Handling Precautions

1. Allowable Creepage Dimensions at Time of Mating

[Stacking height : 2mm]

The effective coupling length of this product is 0.55mm for the signal portion and the ground portion. The creepage of the header and receptacle at the time of mating should be within 0.18mm of the completely coupled condition.

2. Compatibility

2mm type and 2.5mm, 3mm type, with ground plate type and without ground type are not mated with each other.

3. Retension of Boards

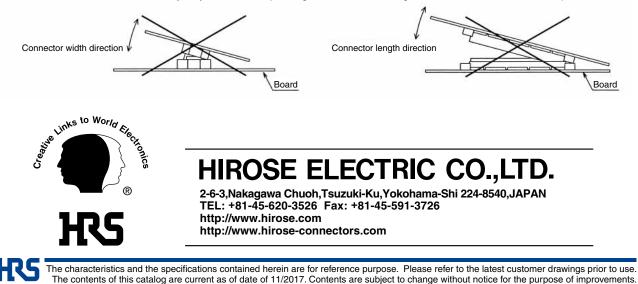
Avoid the support of boards by connectors alone and adopt a board locking measure that does not rely on the connectors.

4. Solder Repair

Flux may rise as far as the contact portion of the connector depending on the flux coating and other factors at the time of repair. This will cause poor contact reliability; therefore, before use, the aforementioned washing conditions should be taken into consideration prior to connector washing.

5. Miscellaneous

Note that excessive twisting while inserting or withdrawing connectors will cause damage. The shade of the molded items may vary somewhat depending on the manufacturing lot; however, this does not affect performance.



HRS test conditions

[Stacking height : 2.5mm, 3mm]

The effective coupling length of this product is 1mm for the

signal portion and 0.9mm for the ground portion. The

creepage of the header and receptacle at the time of mating should be within 0.4mm of the completely coupled condition.

Test boardGlass epoxy 60mm×35mm×1.6mm thick						
Solder method	: Reflow					
Solder composition	: Paste,96.5%Sn/ 3%Ag/ 0.5%Cu					
Metal mask	: 0.15mm thick					
Reflow cycles	: 2 cycles					

The temperature profile is based on the above conditions. In individual applications the actual temperature may vary, depending on solder paste type, volume/thickness and board size/thickness. Consult your solder paste and equipment manufacturer for specific recommendations.